

CLAIMS

1. A resin composition, capable of being employed for forming a resin layer of a resin-attached metal foil, comprising:

5 a cyanate resin and/or a prepolymer thereof;
an epoxy resin substantially containing no halogen atom;
a phenoxy resin substantially containing no halogen atom;
an imidazole compound; and
an inorganic filler.

10 2. A resin composition, capable of being employed for forming an insulating sheet of a base material-attached insulating sheet, comprising:

a cyanate resin and/or a prepolymer thereof;
15 an epoxy resin substantially containing no halogen atom;
a phenoxy resin substantially containing no halogen atom;
an imidazole compound; and
an inorganic filler.

20 3. The resin composition according to claim 1 or 2, wherein said cyanate resin is a novolac cyanate resin.

4. The resin composition according to any one of claims 1 to 3, wherein said epoxy resin is an aryl alkylene epoxy resin.

25 5. The resin composition according to any one of claims 1 to 4, wherein said imidazole compound has two or more functional groups

selected from a group consisting of aliphatic hydrocarbon group, aromatic hydrocarbon group, hydroxyalkyl group and cyano alkyl group.

5 6. A resin-attached metal foil, formed by cladding a metal foil with the resin composition according to any one of claims 1 to 5.

7. A multiple-layered printed wiring board, formed by laying the resin-attached metal foil(s) according to claim 6 on a single
10 side or both sides of an internal layer circuit board and hot pressure forming thereof.

8. A base material-attached insulating sheet, formed by cladding an insulating base material with the resin composition
15 according to any one of claims 1 to 5.

9. A multiple-layered printed wiring board, formed by laying the base material-attached insulating sheet(s) according to claim 8 on a single side or both sides of an internal layer circuit
20 board and hot pressure forming thereof.